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W25Q32JW



*spi*flash[®]

**1.8V 32M-BIT
SERIAL FLASH MEMORY WITH
DUAL, QUAD SPI**



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1. GENERAL DESCRIPTIONS

The W25Q32JW (32M-bit) Serial Flash memory provides a storage solution for systems with limited space, pins and power. The 25Q series offers flexibility and performance well beyond ordinary Serial Flash devices. They are ideal for code shadowing to RAM, executing code directly from Dual/Quad SPI (XIP) and storing voice, text and data. The device operates on 1.7V to 1.95V power supply with current consumption as low as 0.1µA for power-down.

The W25Q32JW array is organized into 16,384 programmable pages of 256-bytes each. Up to 256 bytes can be programmed at a time. Pages can be erased in groups of 16 (4KB sector erase), groups of 128 (32KB block erase), groups of 256 (64KB block erase) or the entire chip (chip erase). The W25Q32JW has 1,024 erasable sectors and 64 erasable blocks respectively. The small 4KB sectors allow for greater flexibility in applications that require data and parameter storage. (See Figure 2.)

The W25Q32JW supports the standard Serial Peripheral Interface (SPI), and a high performance Dual/Quad output as well as Dual/Quad I/O SPI: Serial Clock, Chip Select, Serial Data I/O0 (DI), I/O1 (DO), I/O2, and I/O3. SPI clock frequencies of up to 133MHz are supported allowing equivalent clock rates of 266MHz (133MHz x 2) for Dual I/O and 532MHz (133MHz x 4) for Quad I/O when using the Fast Read Dual/Quad I/O instructions. These transfer rates can outperform standard Asynchronous 8 and 16-bit Parallel Flash memories.

Additionally, the device supports JEDEC standard manufacturer and device ID and SFDP Register, a 64-bit Unique Serial Number and three 256-bytes Security Registers.

2. FEATURES

- **New Family of SpiFlash Memories**
 - W25Q32JW: 32M-bit / 4M-byte
 - Standard SPI: CLK, /CS, DI, DO
 - Dual SPI: CLK, /CS, IO₀, IO₁,
 - Quad SPI: CLK, /CS, IO₀, IO₁, IO₂, IO₃
 - Software & Hardware Reset⁽¹⁾
- **Highest Performance Serial Flash**
 - 133MHz Single, Dual/Quad SPI clocks
 - 266/532MHz equivalent Dual/Quad SPI
 - 66MB/S continuous data transfer rate
 - Min. 100K Program-Erase cycles per sector
 - More than 20-year data retention
- **Efficient “Continuous Read”**
 - As few as 8 clocks to address memory
 - Allows true XIP (execute in place) operation
 - Outperforms X16 Parallel Flash
- **Low Power, Wide Temperature Range**
 - Single 1.7V to 1.95V supply
 - <0.1µA Power-down (typ.)
 - -40°C to +85°C operating range
- **Flexible Architecture with 4KB sectors**
 - Uniform Sector/Block Erase (4K/32K/64K-Byte)
 - Program 1 to 256 byte per programmable page
 - Erase/Program Suspend & Resume
- **Advanced Security Features**
 - Software and Hardware Write-Protect
 - Special OTP protection⁽²⁾
 - Top/Bottom, Complement array protection
 - Individual Block/Sector array protection
 - 64-Bit Unique ID for each device
 - Discoverable Parameters (SFDP) Register
 - 3X256-Bytes Security Registers
 - Volatile & Non-volatile Status Register Bits
- **Space Efficient Packaging**
 - 8-pin SOIC 150/208-mil
 - 8-pad XSON 4x4-mm
 - 8-pad WSON 6x5-mm / USON 4x3-mm
 - 24-ball TFBGA 8x6-mm (6x4/5x5 ball array)
 - 12-ball WLCSP
 - Contact Winbond for KGD and other options

Note: 1. Hardware /RESET pin is only available on SOIC-16 & TFBGA packages
 2. Please contact Winbond for details.



3. PACKAGE TYPES AND PIN CONFIGURATIONS

3.1 Pin Configuration SOIC 150-mil / 208-mil

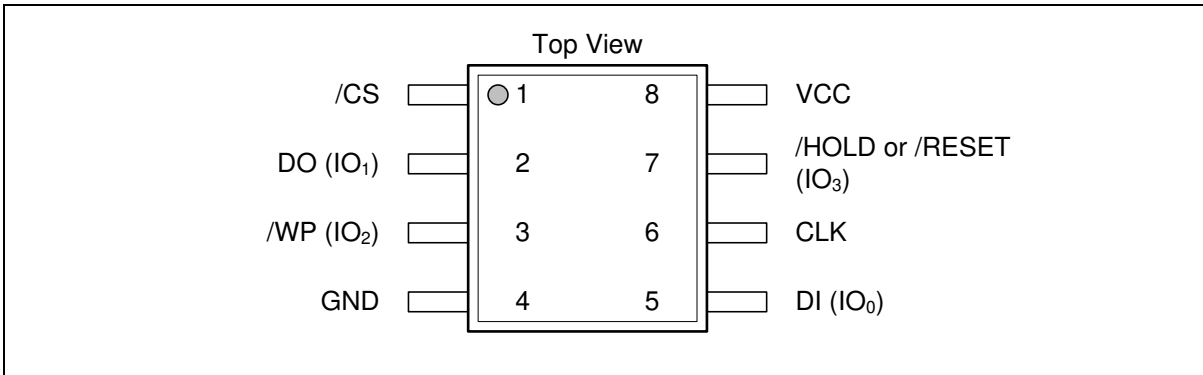


Figure 1a. W25Q32JW Pin Assignments, 8-pin SOIC150-mil/ 208-mil (Package Code SN, SS)

3.2 Pad Configuration WSON 6x5-mm, XSON 4x4-mm, USON4x3-mm

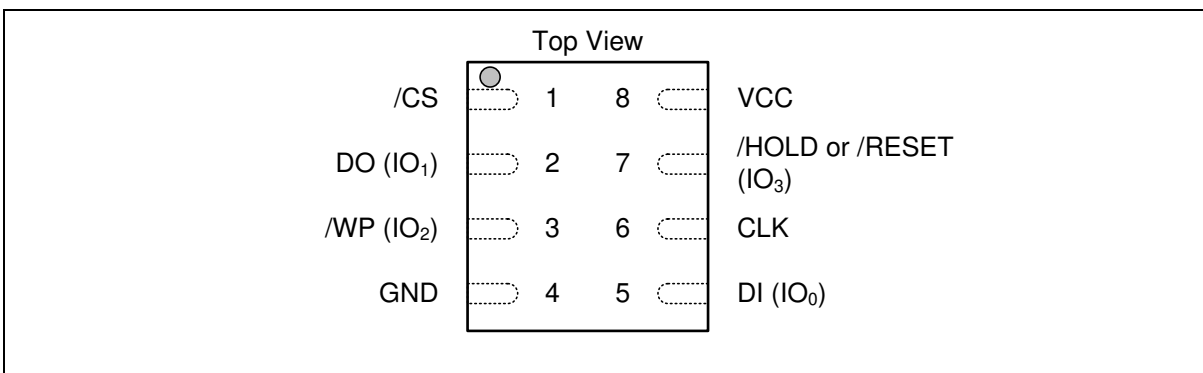


Figure 1b. W25Q32JW Pad Assignments, 8-pad WSON 6x5-mm (Package Code ZP, XG)

3.3 Pin Description SOIC 150/208-mil, WSON 6x5-mm, XSON 4x4-mm, USON4x3-mm

PAD NO.	PAD NAME	I/O	FUNCTION
1	/CS	I	Chip Select Input
2	DO (IO ₁)	I/O	Data Output (Data Input Output 1) ⁽¹⁾
3	/WP (IO ₂)	I/O	Write Protect Input (Data Input Output 2) ⁽²⁾
4	GND		Ground
5	DI (IO ₀)	I/O	Data Input (Data Input Output 0) ⁽¹⁾
6	CLK	I	Serial Clock Input
7	/HOLD or /RESET (IO ₃)	I/O	Hold or Reset Input (Data Input Output 3) ⁽²⁾
8	VCC		Power Supply

Notes:

- IO₀ and IO₁ are used for Standard and Dual SPI instructions
- IO₀ – IO₃ are used for Quad SPI instructions, /HOLD (or /RESET) function is only available for Standard/Dual SPI.



3.4 Ball Configuration TFBGA 8x6-mm (5x5 or 6x4 Ball Array)

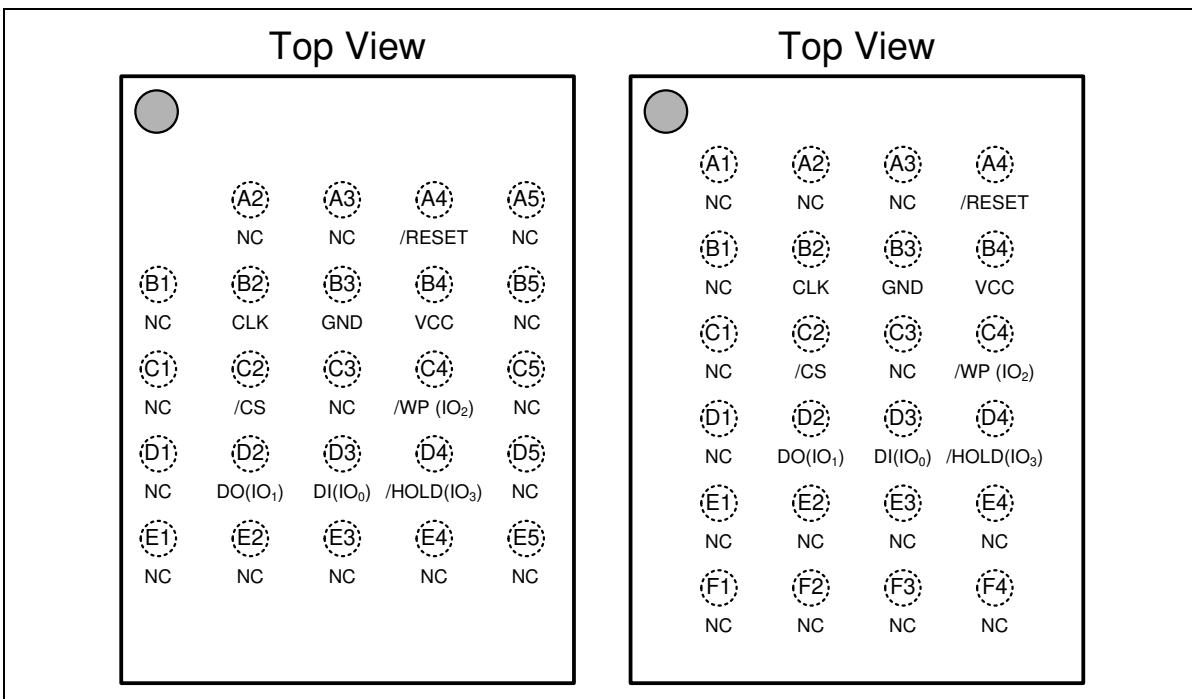


Figure 1c. W25Q32JW Ball Assignments, 24-ball TFBGA 8x6-mm, 5X5 and 6x4 (Package Code TB, TC)

3.5 Ball Description TFBGA 8x6-mm

BALL NO.	PIN NAME	I/O	FUNCTION
A4	/RESET	I	Reset Input ⁽³⁾
B2	CLK	I	Serial Clock Input
B3	GND		Ground
B4	VCC		Power Supply
C2	/CS	I	Chip Select Input
C4	/WP (IO ₂)	I/O	Write Protect Input (Data Input Output 2) ⁽²⁾
D2	DO (IO ₁)	I/O	Data Output (Data Input Output 1) ⁽¹⁾
D3	DI (IO ₀)	I/O	Data Input (Data Input Output 0) ⁽¹⁾
D4	/HOLD or /RESET (IO ₃)	I/O	Hold or Reset Input (Data Input Output 3) ⁽²⁾
Multiple	NC		No Connect

Notes:

- IO₀ and IO₁ are used for Standard and Dual SPI instructions
- IO₀ – IO₃ are used for Quad SPI instructions, /HOLD (or /RESET) function is only available for Standard/Dual SPI.
- The /RESET pin is a dedicated hardware reset pin regardless of device settings or operation states.
If the hardware reset function is not used, this pin can be left floating or connected to VCC in the system



3.6 Ball Configuration WLCSP

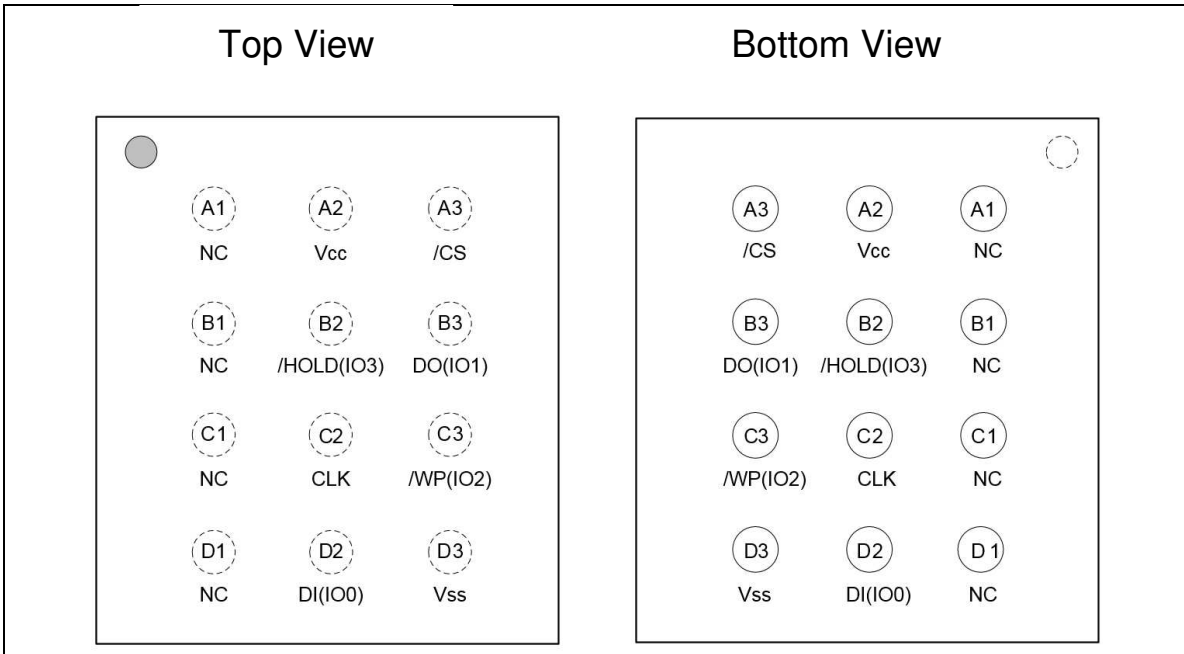


Figure 1d. W25Q32JW Ball Assignments, 12-ball WLCSP (Package Code BY)

3.7 Ball Description WLCSP12

BALL NO.	PIN NAME	I/O	FUNCTION
A2	VCC		Power Supply
B2	/HOLD or /RESET (IO3)	I/O	Hold Input or /RESET (Data Input Output 3) ⁽²⁾
C2	CLK	I	Serial Clock Input
D2	DI (IO0)	I/O	Data Input (Data Input Output 0) ⁽¹⁾
A3	/CS	I	Chip Select Input
B3	DO (IO1)	I/O	Data Output (Data Input Output 1) ⁽¹⁾
C3	/WP (IO2)	I/O	Write Protect Input (Data Input Output 2) ⁽²⁾
D3	GND		Ground
Multiple	NC		No Connect

Notes:

- IO0 and IO1 are used for Standard and Dual SPI instructions
- IO0 – IO3 are used for Quad SPI instructions, /WP & /HOLD (or /RESET) functions are only available for Standard/Dual SPI.

4. PIN DESCRIPTIONS



4.1 Chip Select (/CS)

The SPI Chip Select (/CS) pin enables and disables device operation. When /CS is high the device is deselected and the Serial Data Output (DO, or IO0, IO1, IO2, IO3) pins are at high impedance. When deselected, the device's power consumption will be at standby levels unless an internal erase, program or write status register cycle is in progress. When /CS is brought low the device will be selected, power consumption will increase to active levels and instructions can be written to and data read from the device. After power-up, /CS must transition from high to low before a new instruction will be accepted. The /CS input must track the VCC supply level at power-up and power-down (see "Write Protection" and Figure 58). If needed a pull-up resistor on the /CS pin can be used to accomplish this.

4.2 Serial Data Input, Output and IOs (DI, DO and IO0, IO1, IO2, IO3)

The Q32JW supports standard SPI, Dual SPI and Quad SPI operation. Standard SPI instructions use the unidirectional DI (input) pin to serially write instructions, addresses or data to the device on the rising edge of the Serial Clock (CLK) input pin. Standard SPI also uses the unidirectional DO (output) to read data or status from the device on the falling edge of CLK.

Dual and Quad SPI instructions use the bidirectional IO pins to serially write instructions, addresses or data to the device on the rising edge of CLK and read data or status from the device on the falling edge of CLK. Quad SPI instructions require the non-volatile Quad Enable bit (QE) in Status Register-2 to be set. When QE=1, the /WP pin becomes IO2 and the /HOLD pin becomes IO3.

4.3 Write Protect (/WP)

The Write Protect (/WP) pin can be used to prevent the Status Register from being written. Used in conjunction with the Status Register's Block Protect (CMP, SEC, TB, BP2, BP1 and BP0) bits and Status Register Protect (SRP) bits, a portion as small as a 4KB sector or the entire memory array can be hardware protected. The /WP pin is active low.

4.4 HOLD (/HOLD)

The /HOLD pin allows the device to be paused while it is actively selected. When /HOLD is brought low, while /CS is low, the DO pin will be at high impedance and signals on the DI and CLK pins will be ignored (don't care). When /HOLD is brought high, device operation can resume. The /HOLD function can be useful when multiple devices are sharing the same SPI signals. The /HOLD pin is active low. When the QE bit of Status Register-2 is set for Quad I/O, the /HOLD pin function is not available since this pin is used for IO3. See Figure 1a-c for the pin configuration of Quad I/O operation.

4.5 Serial Clock (CLK)

The SPI Serial Clock Input (CLK) pin provides the timing for serial input and output operations. ("See SPI Operations")

4.6 Reset (/RESET)⁽¹⁾

A dedicated hardware /RESET pin is available on SOIC-16 and TFBGA packages. When it's driven low for a minimum period of ~1 μ S, this device will terminate any external or internal operations and return to its power-on state.

Note:

1. Hardware /RESET pin is available on SOIC-16 or TFBGA; please contact Winbond for this package.

5. BLOCK DIAGRAM

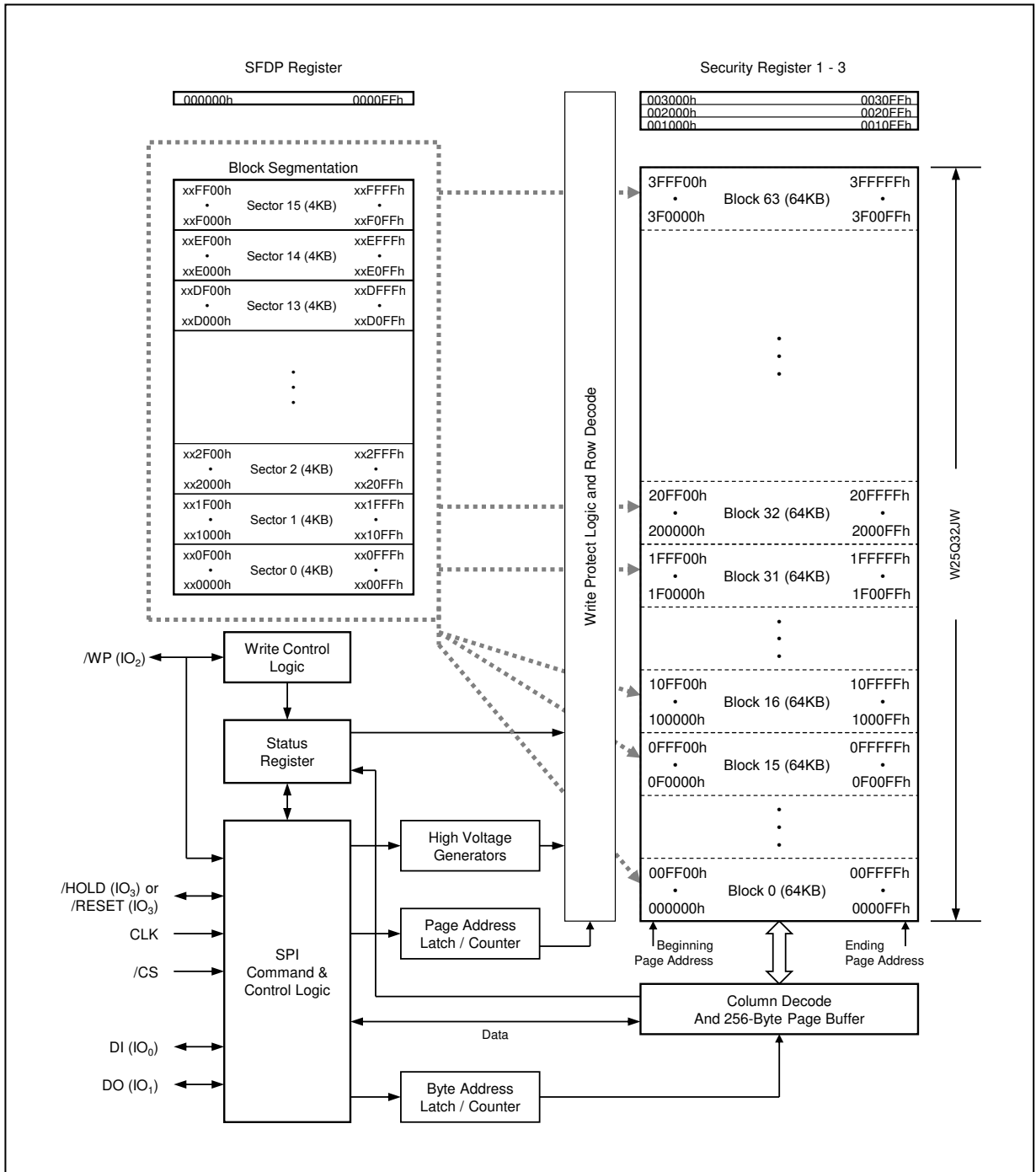


Figure 2. W25Q32JW Serial Flash Memory Block Diagram



6. FUNCTIONAL DESCRIPTIONS

6.1 Standard SPI Instructions

The W25Q32JW is accessed through an SPI compatible bus consisting of four signals: Serial Clock (CLK), Chip Select (/CS), Serial Data Input (DI) and Serial Data Output (DO). Standard SPI instructions use the DI input pin to serially write instructions, addresses or data to the device on the rising edge of CLK. The DO output pin is used to read data or status from the device on the falling edge of CLK.

SPI bus operation Mode 0 (0,0) and 3 (1,1) are supported. The primary difference between Mode 0 and Mode 3 concerns the normal state of the CLK signal when the SPI bus master is in standby and data is not being transferred to the Serial Flash. For Mode 0, the CLK signal is normally low on the falling and rising edges of /CS. For Mode 3, the CLK signal is normally high on the falling and rising edges of /CS.

6.2 Dual SPI Instructions

The W25Q32JW supports Dual SPI operation when using instructions such as “Fast Read Dual Output (3Bh)” and “Fast Read Dual I/O (BBh)”. These instructions allow data to be transferred to or from the device at two to three times the rate of ordinary Serial Flash devices. The Dual SPI Read instructions are ideal for quickly downloading code to RAM upon power-up (code-shadowing) or for executing non-speed-critical code directly from the SPI bus (XIP). When using Dual SPI instructions, the DI and DO pins become bidirectional I/O pins: IO0 and IO1.

6.3 Quad SPI Instructions

The W25Q32JW supports Quad SPI operation when using instructions such as “Fast Read Quad Output (6Bh)”, and “Fast Read Quad I/O (EBh)”. These instructions allow data to be transferred to or from the device four to six times the rate of ordinary Serial Flash. When using Quad SPI instructions, the DI and DO pins become bidirectional IO0 and IO1, with the additional I/O pins: IO2, IO3.

6.4 Software Reset & Hardware /RESET pin

The W25Q32JW can be reset to the initial power-on state by a software Reset sequence. This sequence must include two consecutive instructions: Enable Reset (66h) & Reset (99h). If the instruction sequence is successfully accepted, the device will take approximately 30 μ S (t_{RST}) to reset. No instruction will be accepted during the reset period. For the SOIC-16 and TFBGA packages, W25Q32JW provides a dedicated hardware /RESET pin. Drive the /RESET pin low for a minimum period of \sim 1 μ S (t_{RESET}^*) will interrupt any on-going external/internal operations and reset the device to its initial power-on state. Hardware /RESET pin has higher priority than other SPI input signals (/CS, CLK, IOs).

Note:

1. Hardware /RESET pin is available on SOIC-16 or TFBGA; please contact Winbond for his package.
2. While a faster /RESET pulse (as short as a few hundred nanoseconds) will often reset the device, a 1us minimum is recommended to ensure reliable operation.
3. There is an internal pull-up resistor for the dedicated /RESET pin on the SOIC-16 package. If the reset function is not needed, this pin can be left floating in the system.



6.5 Write Protection

Applications that use non-volatile memory must take into consideration the possibility of noise and other adverse system conditions that may compromise data integrity. To address this concern, the W25Q32JW provides several means to protect the data from inadvertent writes.

6.5.1 Write Protect Features

- Device resets when VCC is below threshold
- Time delay write disable after Power-up
- Write enable/disable instructions and automatic write disable after erase or program
- Software and Hardware (/WP pin) write protection using Status Registers
- Additional Individual Block/Sector Locks for array protection
- Write Protection using Power-down instruction
- Lock Down write protection for Status Register until the next power-up
- One Time Program (OTP) write protection for array and Security Registers using Status Register*

* Note: This feature is available upon special order. Please contact Winbond for details.

Upon power-up or at power-down, the W25Q32JW will maintain a reset condition while VCC is below the threshold value of V_{WI} , (See Power-up Timing and Voltage Levels and Figure 43). While reset, all operations are disabled and no instructions are recognized. During power-up and after the VCC voltage exceeds V_{WI} , all program and erase related instructions are further disabled for a time delay of t_{PUW} . This includes the Write Enable, Page Program, Sector Erase, Block Erase, Chip Erase and the Write Status Register instructions. Note that the chip select pin (/CS) must track the VCC supply level at power-up until the VCC-min level and t_{VSL} time delay is reached, and it must also track the VCC supply level at power-down to prevent adverse command sequence. If needed a pull-up resistor on /CS can be used to accomplish this.

After power-up the device is automatically placed in a write-disabled state with the Status Register Write Enable Latch (WEL) set to a 0. A Write Enable instruction must be issued before a Page Program, Sector Erase, Block Erase, Chip Erase or Write Status Register instruction will be accepted. After completing a program, erase or write instruction the Write Enable Latch (WEL) is automatically cleared to a write-disabled state of 0.

Software controlled write protection is facilitated using the Write Status Register instruction and setting the Status Register Protect (SRP, SRL) and Block Protect (CMP, TB, BP[2:0]) bits. These settings allow a portion or the entire memory array to be configured as read only. Used in conjunction with the Write Protect (/WP) pin, changes to the Status Register can be enabled or disabled under hardware control. See Status Register section for further information. Additionally, the Power-down instruction offers an extra level of write protection as all instructions are ignored except for the Release Power-down instruction.

The W25Q32JW also provides another Write Protect method using the Individual Block Locks. Each 64KB block (except the top and bottom blocks, total of 62 blocks) and each 4KB sector within the top/bottom blocks (total of 32 sectors) are equipped with an Individual Block Lock bit. When the lock bit is 0, the corresponding sector or block can be erased or programmed; when the lock bit is set to 1, Erase or Program commands issued to the corresponding sector or block will be ignored. When the device is powered on, all Individual Block Lock bits will be 1, so the entire memory array is protected from Erase/Program. An "Individual Block Unlock (39h)" instruction must be issued to unlock any specific sector or block.

The WPS bit in Status Register-3 is used to decide which Write Protect scheme should be used. When $WPS=0$ (factory default), the device will only utilize CMP, SEC, TB, BP[2:0] bits to protect specific areas of the array; when $WPS=1$, the device will utilize the Individual Block Locks for write protection.



7. STATUS AND CONFIGURATION REGISTERS

Three Status and Configuration Registers are provided for W25Q32JW. The Read Status Register-1/2/3 instructions can be used to provide status on the availability of the flash memory array, whether the device is write enabled or disabled, the state of write protection, Quad SPI setting, Security Register lock status, Erase/Program Suspend status, and output driver strength. The Write Status Register instruction can be used to configure the device write protection features, Quad SPI setting, Security Register OTP locks, and output driver strength. Write access to the Status Register is controlled by the state of the non-volatile Status Register Protect bits (SRL), the Write Enable instruction, and during Standard/Dual SPI operations.

7.1 Status Registers

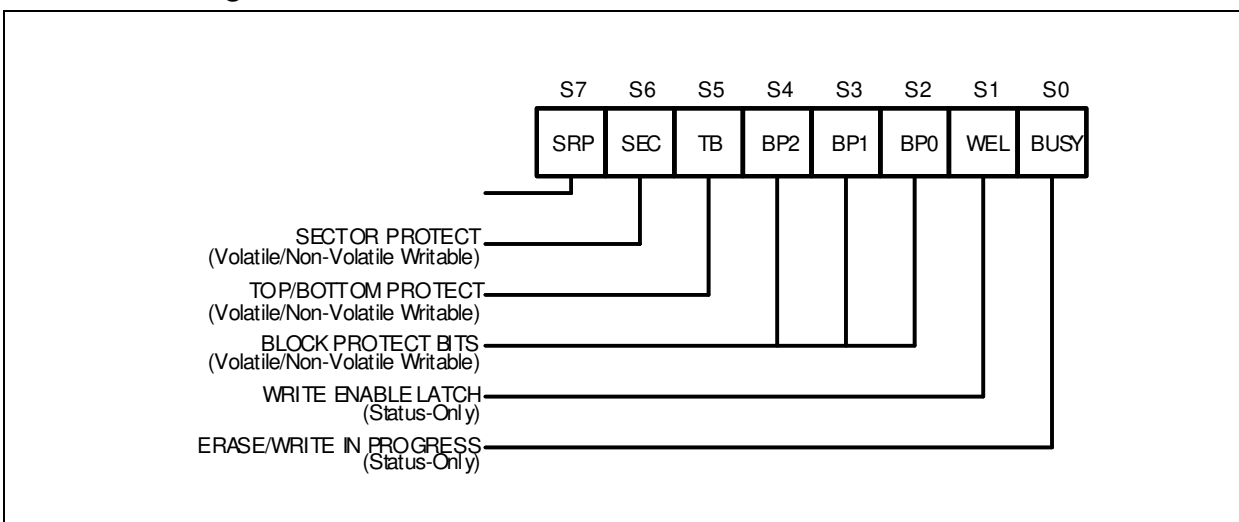


Figure 4a. Status Register-1

7.1.1 Erase/Write In Progress (BUSY) – Status Only

BUSY is a read only bit in the status register (S0) that is set to a 1 state when the device is executing a Page Program, Quad Page Program, Sector Erase, Block Erase, Chip Erase, Write Status Register or Erase/Program Security Register instruction. During this time the device will ignore further instructions except for the Read Status Register and Erase/Program Suspend instruction (see t_w , t_{PP} , t_{SE} , t_{BE} , and t_{CE} in AC Characteristics). When the program, erase or write status/security register instruction has completed, the BUSY bit will be cleared to a 0 state indicating the device is ready for further instructions.

7.1.2 Write Enable Latch (WEL) – Status Only

Write Enable Latch (WEL) is a read only bit in the status register (S1) that is set to 1 after executing a Write Enable Instruction. The WEL status bit is cleared to 0 when the device is write disabled. A write disable state occurs upon power-up or after any of the following instructions: Write Disable, Page Program, Quad Page Program, Sector Erase, Block Erase, Chip Erase, Write Status Register, Erase Security Register and Program Security Register.

7.1.3 Block Protect Bits (BP2, BP1, BP0) – Volatile/Non-Volatile Writable

The Block Protect Bits (BP2, BP1, BP0) are non-volatile read/write bits in the status register (S4, S3, and S2) that provide Write Protection control and status. Block Protect bits can be set using the Write Status Register Instruction (see t_w in AC characteristics). All, none or a portion of the memory array can be protected from Program and Erase instructions (see Status Register Memory Protection table). The factory default setting for the Block Protection Bits is 0, none of the array protected.



7.1.4 Top/Bottom Block Protect (TB) – *Volatile/Non-Volatile Writable*

The non-volatile Top/Bottom bit (TB) controls if the Block Protect Bits (BP2, BP1, BP0) protect from the Top (TB=0) or the Bottom (TB=1) of the array as shown in the Status Register Memory Protection table. The factory default setting is TB=0. The TB bit can be set with the Write Status Register Instruction depending on the state of the SRL and WEL bits.

7.1.5 Sector/Block Protect Bit (SEC) – *Volatile/Non-Volatile Writable*

The non-volatile Sector/Block Protect bit (SEC) controls if the Block Protect Bits (BP2, BP1, BP0) protect either 4KB Sectors (SEC=1) or 64KB Blocks (SEC=0) in the Top (TB=0) or the Bottom (TB=1) of the array as shown in the Status Register Memory Protection table. The default setting is SEC=0.

7.1.6 Complement Protect (CMP) – *Volatile/Non-Volatile Writable*

The Complement Protect bit (CMP) is a non-volatile read/write bit in the status register (S14). It is used in conjunction with SEC, TB, BP2, BP1 and BP0 bits to provide more flexibility for the array protection. Once CMP is set to 1, previous array protection set by SEC, TB, BP2, BP1 and BP0 will be reversed. For instance, when CMP=0, a top 64KB block can be protected while the rest of the array is not; when CMP=1, the top 64KB block will become unprotected while the rest of the array become read-only. Please refer to the Status Register Memory Protection table for details. The default setting is CMP=0.



7.1.1 Status Register Protect (SRP, SRL) – Volatile/Non-Volatile Writable

Three Status and Configuration Registers are provided for W25Q32JW. The Read Status Register-1/2/3 instructions can be used to provide status on the availability of the flash memory array, whether the device is write enabled or disabled, the state of write protection, Quad SPI setting, Security Register lock status, Erase/Program Suspend status, and output driver strength, The Write Status Register instruction can be used to configure the device write protection features, Quad SPI setting, Security Register OTP locks, output driver. Write access to the Status Register is controlled by the state of the non-volatile Status Register Protect bits (SRP, SRL), the Write Enable instruction, and during Standard/Dual SPI operations, the /WP pin.

SRL	SRP	/WP	Status Register	Description
0	0	X	Software Protection	/WP pin has no control. The Status register can be written to after a Write Enable instruction, WEL=1. [Factory Default]
0	1	0	Hardware Protected	When /WP pin is low the Status Register locked and cannot be written to.
0	1	1	Hardware Unprotected	When /WP pin is high the Status register is unlocked and can be written to after a Write Enable instruction, WEL=1.
1	X	X	Power Supply Lock-Down	Status Register is protected and cannot be written to again until the next power-down, power-up cycle. ⁽¹⁾
1	X	X	One Time Program ⁽²⁾	Status Register is permanently protected and cannot be written to. (enabled by adding prefix command AAh, 55h)

1. When SRL =1 , a power-down, power-up cycle will change SRL =0 state.
2. Please contact Winbond for details regarding the special instruction sequence.

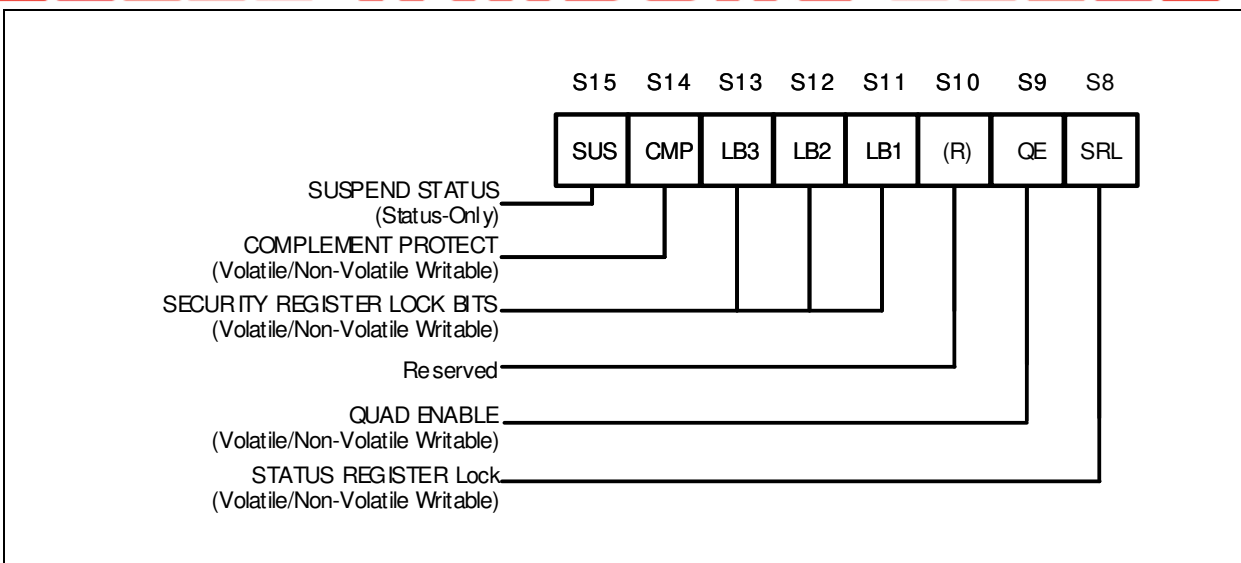


Figure 4b. Status Register-2

7.1.2 Erase/Program Suspend Status (SUS) – Status Only

The Suspend Status bit is a read only bit in the status register (S15) that is set to 1 after executing a Erase/Program Suspend (75h) instruction. The SUS status bit is cleared to 0 by Erase/Program Resume (7Ah) instruction as well as a power-down, power-up cycle.

7.1.3 Security Register Lock Bits (LB3, LB2, LB1) – Volatile/Non-Volatile OTP Writable

The Security Register Lock Bits (LB3, LB2, LB1) are non-volatile One Time Program (OTP) bits in Status Register (S13, S12, S11) that provide the write protect control and status to the Security Registers. The default state of LB3-1 is 0, Security Registers are unlocked. LB3-1 can be set to 1 individually using the Write Status Register instruction. LB3-1 are One Time Programmable (OTP), once it's set to 1, the corresponding 256-Byte Security Register will become read-only permanently.

7.1.4 Quad Enable (QE) – Volatile/Non-Volatile Writable

The Quad Enable (QE) bit is a non-volatile read/write bit in the status register (S9) that enables Quad SPI operation. When the QE bit is set to a 0 state (factory default for part numbers with ordering options "IM"), the /HOLD are enabled, the device operates in Standard/Dual SPI modes. When the QE bit is set to a 1 (factory fixed default for part numbers with ordering options "IQ"), the Quad IO2 and IO3 pins are enabled, and /HOLD function is disabled, the device operates in Standard/Dual/Quad SPI modes.

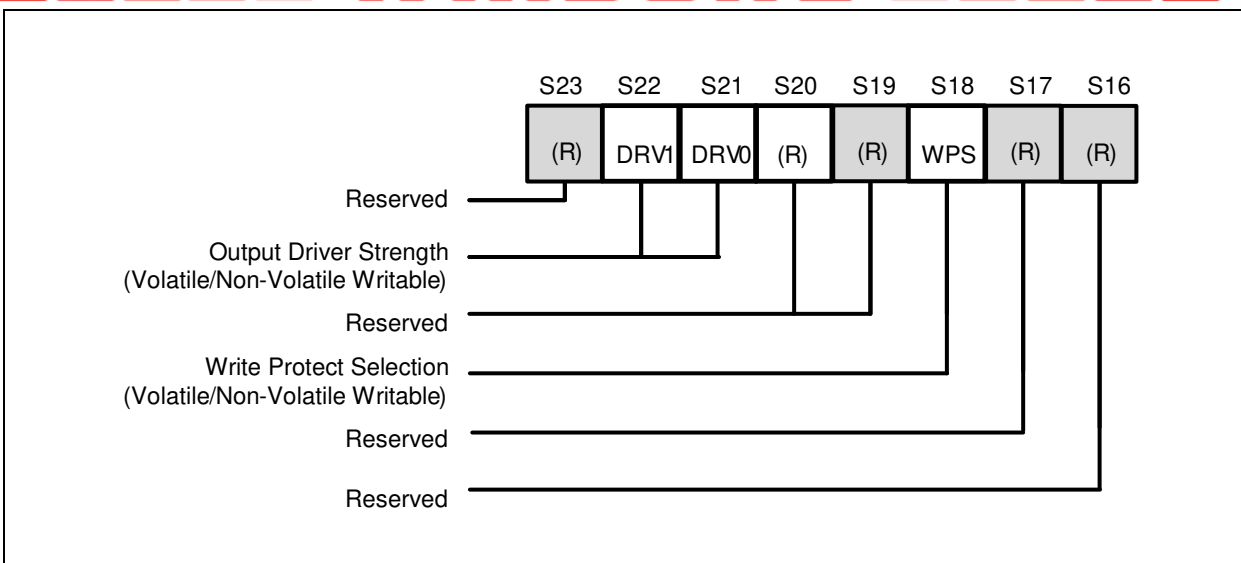


Figure 4c. Status Register-3

7.1.5 Write Protect Selection (WPS) – *Volatile/Non-Volatile Writable*

The WPS bit is used to select which Write Protect scheme should be used. When WPS=0, the device will use the combination of CMP, SEC, TB, BP[2:0] bits to protect a specific area of the memory array. When WPS=1, the device will utilize the Individual Block Locks to protect any individual sector or blocks. The default value for all Individual Block Lock bits is 1 upon device power on or after reset.

7.1.6 Output Driver Strength (DRV1, DRV0) – *Volatile/Non-Volatile Writable*

The DRV1 & DRV0 bits are used to determine the output driver strength for the Read operations.

DRV1, DRV0	Driver Strength
0, 0	100%
0, 1	75%
1, 0	50%
1, 1	25% (default)

7.1.7 Reserved Bits – *Non Functional*

There are a few reserved Status Register bits that may be read out as a “0” or “1”. It is recommended to ignore the values of those bits. During a “Write Status Register” instruction, the Reserved Bits can be written as “0”, but there will not be any effects.



7.1.8 Status Register Memory Protection (WPS = 0, CMP = 0)

STATUS REGISTER ⁽¹⁾					W25Q32JW (32M-BIT) MEMORY PROTECTION ⁽³⁾			
SEC	TB	BP2	BP1	BP0	PROTECTED BLOCK(S)	PROTECTED ADDRESSES	PROTECTED DENSITY	PROTECTED PORTION ⁽²⁾
X	X	0	0	0	NONE	NONE	NONE	NONE
0	0	0	0	1	63	3F0000h – 3FFFFFFh	64KB	Upper 1/64
0	0	0	1	0	62 and 63	3E0000h – 3FFFFFFh	128KB	Upper 1/32
0	0	0	1	1	60 thru 63	3C0000h – 3FFFFFFh	256KB	Upper 1/16
0	0	1	0	0	56 thru 63	380000h – 3FFFFFFh	512KB	Upper 1/8
0	0	1	0	1	48 thru 63	300000h – 3FFFFFFh	1MB	Upper 1/4
0	0	1	1	0	32 thru 63	200000h – 3FFFFFFh	2MB	Upper 1/2
0	1	0	0	1	0	000000h – 00FFFFh	64KB	Lower 1/64
0	1	0	1	0	0 and 1	000000h – 01FFFFh	128KB	Lower 1/32
0	1	0	1	1	0 thru 3	000000h – 03FFFFh	256KB	Lower 1/16
0	1	1	0	0	0 thru 7	000000h – 07FFFFh	512KB	Lower 1/8
0	1	1	0	1	0 thru 15	000000h – 0FFFFFFh	1MB	Lower 1/4
0	1	1	1	0	0 thru 31	000000h – 1FFFFFFh	2MB	Lower 1/2
X	X	1	1	1	0 thru 63	000000h – 3FFFFFFh	4MB	ALL
1	0	0	0	1	63	3FF000h – 3FFFFFFh	4KB	U - 1/1024
1	0	0	1	0	63	3FE000h – 3FFFFFFh	8KB	U - 1/512
1	0	0	1	1	63	3FC000h – 3FFFFFFh	16KB	U - 1/256
1	0	1	0	X	63	3F8000h – 3FFFFFFh	32KB	U - 1/128
1	1	0	0	1	0	000000h – 000FFFh	4KB	L - 1/1024
1	1	0	1	0	0	000000h – 001FFFh	8KB	L - 1/512
1	1	0	1	1	0	000000h – 003FFFh	16KB	L - 1/256
1	1	1	0	X	0	000000h – 007FFFh	32KB	L - 1/128

Notes:

1. X = don't care
2. L = Lower; U = Upper
3. If any Erase or Program command specifies a memory region that contains protected data portion, this command will be ignored.



7.1.9 Status Register Memory Protection (WPS = 0, CMP = 1)

STATUS REGISTER ⁽¹⁾					W25Q32JW (32M-BIT) MEMORY PROTECTION ⁽³⁾			
SEC	TB	BP2	BP1	BP0	PROTECTED BLOCK(S)	PROTECTED ADDRESSES	PROTECTED DENSITY	PROTECTED PORTION ⁽²⁾
X	X	0	0	0	0 thru 63	000000h – 3FFFFFFh	4MB	ALL
0	0	0	0	1	0 thru 62	000000h – 3EFFFFh	4,032KB	Lower 63/64
0	0	0	1	0	0 and 61	000000h – 3DFFFFh	3,968KB	Lower 31/32
0	0	0	1	1	0 thru 59	000000h – 3BFFFFh	3,840KB	Lower 15/16
0	0	1	0	0	0 thru 55	000000h – 37FFFFh	3,584KB	Lower 7/8
0	0	1	0	1	0 thru 47	000000h – 2FFFFFFh	3MB	Lower 3/4
0	0	1	1	0	0 thru 31	000000h – 1FFFFFFh	2MB	Lower 1/2
0	1	0	0	1	1 thru 63	010000h – 3FFFFFFh	4,032KB	Upper 63/64
0	1	0	1	0	2 and 63	020000h – 3FFFFFFh	3,968KB	Upper 31/32
0	1	0	1	1	4 thru 63	040000h – 3FFFFFFh	3,840KB	Upper 15/16
0	1	1	0	0	8 thru 63	080000h – 3FFFFFFh	3,584KB	Upper 7/8
0	1	1	0	1	16 thru 63	100000h – 3FFFFFFh	3MB	Upper 3/4
0	1	1	1	0	32 thru 63	200000h – 3FFFFFFh	2MB	Upper 1/2
X	X	1	1	1	NONE	NONE	NONE	NONE
1	0	0	0	1	0 thru 63	000000h – 3FEFFFh	4,092KB	L - 1023/1024
1	0	0	1	0	0 thru 63	000000h – 3FDFFFh	4,088KB	L - 511/512
1	0	0	1	1	0 thru 63	000000h – 3FBFFFh	4,080KB	L - 255/256
1	0	1	0	X	0 thru 63	000000h – 3F7FFFh	4,064KB	L - 127/128
1	1	0	0	1	0 thru 63	001000h – 3FFFFFFh	4,092KB	U - 1023/1024
1	1	0	1	0	0 thru 63	002000h – 3FFFFFFh	4,088KB	U - 511/512
1	1	0	1	1	0 thru 63	004000h – 3FFFFFFh	4,080KB	U - 255/256
1	1	1	0	X	0 thru 63	008000h – 3FFFFFFh	4,064KB	U - 127/128

Notes:

1. X = don't care
2. L = Lower; U = Upper
3. If any Erase or Program command specifies a memory region that contains protected data portion, this command will be ignored.



7.1.10 Individual Block Memory Protection (WPS=1)

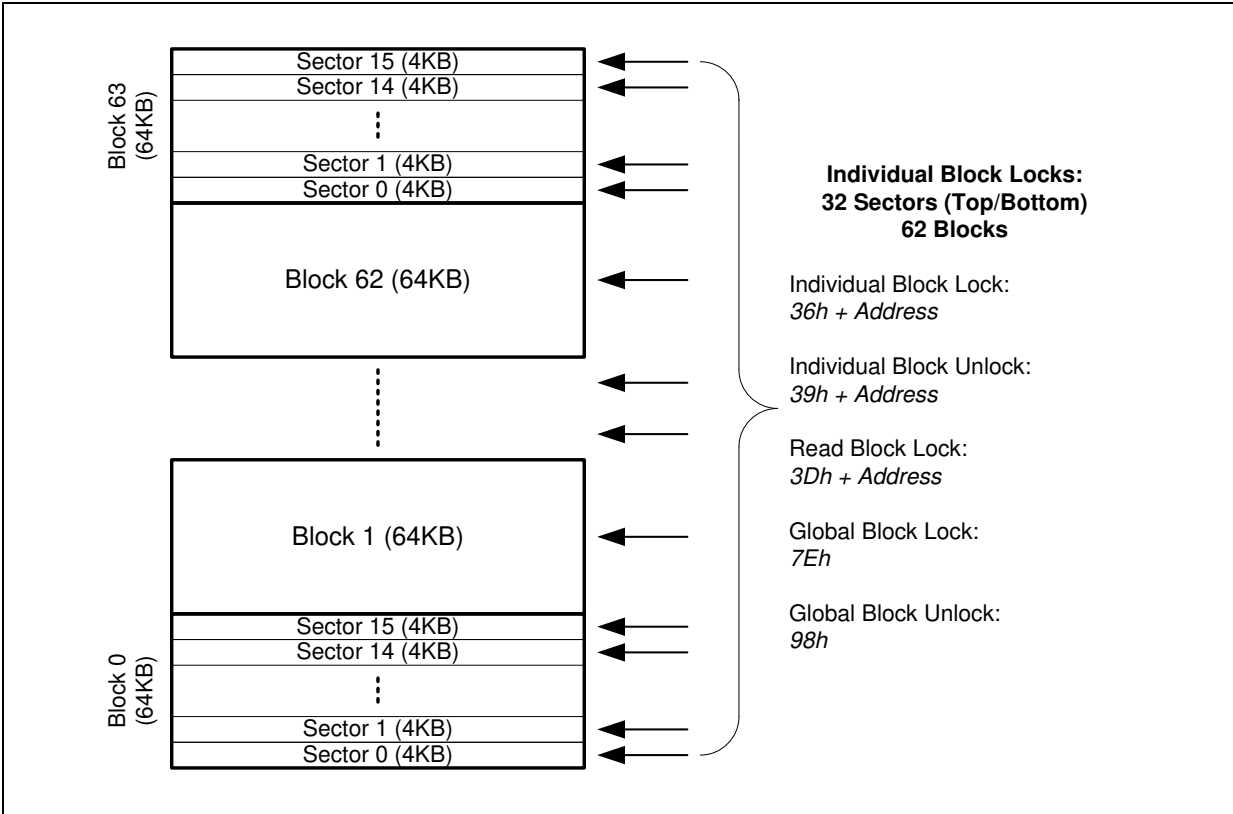


Figure 4d. Individual Block/Sector Locks

Notes:

1. Individual Block/Sector protection is only valid when WPS=1.
2. All individual block/sector lock bits are set to 1 by default after power up, all memory array is protected.



8. INSTRUCTIONS

The Standard/Dual/Quad SPI instruction set of the W25Q32JW consists of 48 basic instructions that are fully controlled through the SPI bus (see Instruction Set Table1-2). Instructions are initiated with the falling edge of Chip Select (/CS). The first byte of data clocked into the DI input provides the instruction code. Data on the DI input is sampled on the rising edge of clock with most significant bit (MSB) first.

Instructions vary in length from a single byte to several bytes and may be followed by address bytes, data bytes, dummy bytes (don't care), and in some cases, a combination. Instructions are completed with the rising edge of edge /CS. Clock relative timing diagrams for each instruction are included in Figures 5 through 57. All read instructions can be completed after any clocked bit. However, all instructions that Write, Program or Erase must complete on a byte boundary (/CS driven high after a full 8-bits have been clocked) otherwise the instruction will be ignored. This feature further protects the device from inadvertent writes. Additionally, while the memory is being programmed or erased, or when the Status Register is being written, all instructions except for Read Status Register will be ignored until the program or erase cycle has completed.

8.1 Device ID and Instruction Set Tables

8.1.1 Manufacturer and Device Identification

MANUFACTURER ID	(MF7 - MF0)	
Winbond Serial Flash	EFh	
Device ID	(ID7 - ID0)	(ID15 - ID0)
Instruction	ABh, 90h, 92h, 94h	9Fh
W25Q32JW-IQ	15h	6016h
W25Q32JW-IM*	15h	8016h

Note: For DTR, QPI supporting, please refer to W25Q32JW DTR datasheet.

8.1.2 Instruction Set Table 1 (Standard SPI Instructions)⁽¹⁾

Data Input Output	Byte 1	Byte 2	Byte 3	Byte 4	Byte 5	Byte 6	Byte 7
Number of Clock ₍₁₋₁₋₁₎	8	8	8	8	8	8	8
Write Enable	06h						
Volatile SR Write Enable	50h						
Write Disable	04h						
Release Power-down	ABh						
Device ID	ABh	Dummy	Dummy	Dummy	(ID7-ID0) ⁽²⁾		
Manufacturer/Device ID	90h	Dummy	Dummy	00h	(MF7-MF0)	(ID7-ID0)	
JEDEC ID	9Fh	(MF7-MF0)	(ID15-ID8)	(ID7-ID0)			
Read Unique ID	4Bh	Dummy	Dummy	Dummy	Dummy	(UID63-0)	
Read Data	03h	A23-A16	A15-A8	A7-A0	(D7-D0)		
Fast Read	0Bh	A23-A16	A15-A8	A7-A0	Dummy	(D7-D0)	
Page Program	02h	A23-A16	A15-A8	A7-A0	D7-D0	D7-D0 ⁽³⁾	
Sector Erase (4KB)	20h	A23-A16	A15-A8	A7-A0			
Block Erase (32KB)	52h	A23-A16	A15-A8	A7-A0			
Block Erase (64KB)	D8h	A23-A16	A15-A8	A7-A0			
Chip Erase	C7h/60h						
Read Status Register-1	05h	(S7-S0) ⁽²⁾					
Write Status Register-1 ⁽⁴⁾	01h	(S7-S0) ⁽⁴⁾					
Read Status Register-2	35h	(S15-S8) ⁽²⁾					
Write Status Register-2	31h	(S15-S8)					
Read Status Register-3	15h	(S23-S16) ⁽²⁾					
Write Status Register-3	11h	(S23-S16)					
Read SFDP Register	5Ah	A23-A16	A15-A8	A7-A0	dummy	(D7-0)	
Erase Security Register ⁽⁵⁾	44h	A23-A16	A15-A8	A7-A0			
Program Security Register ⁽⁵⁾	42h	A23-A16	A15-A8	A7-A0	D7-D0	D7-D0 ⁽³⁾	
Read Security Register ⁽⁵⁾	48h	A23-A16	A15-A8	A7-A0	Dummy	(D7-D0)	
Global Block Lock	7Eh						
Global Block Unlock	98h						
Read Block Lock	3Dh	A23-A16	A15-A8	A7-A0	(L7-L0)		
Individual Block Lock	36h	A23-A16	A15-A8	A7-A0			
Individual Block Unlock	39h	A23-A16	A15-A8	A7-A0			
Erase / Program Suspend	75h						
Erase / Program Resume	7Ah						
Power-down	B9h						
Enable Reset	66h						
Reset Device	99h						

8.1.3 Instruction Set Table 2 (Dual/Quad SPI Instructions)⁽¹⁾

Data Input Output	Byte 1	Byte 2	Byte 3	Byte 4	Byte 5	Byte 6	Byte 7	Byte 8	Byte 9
Number of Clock ⁽¹⁻¹⁻²⁾	8	8	8	8	4	4	4	4	4
Fast Read Dual Output	3Bh	A23-A16	A15-A8	A7-A0	Dummy	Dummy	(D7-D0) ⁽⁷⁾	...	
Number of Clock ⁽¹⁻²⁻²⁾	8	4	4	4	4	4	4	4	4
Fast Read Dual I/O	BBh	A23-A16 ⁽⁶⁾	A15-A8 ⁽⁶⁾	A7-A0 ⁽⁶⁾	Dummy ⁽¹¹⁾	(D7-D0) ⁽⁷⁾	...		
Mftr./Device ID Dual I/O	92h	A23-A16 ⁽⁶⁾	A15-A8 ⁽⁶⁾	00 ⁽⁶⁾	Dummy ⁽¹¹⁾	(MF7-MF0)	(ID7-ID0) ⁽⁷⁾		
Number of Clock ⁽¹⁻¹⁻⁴⁾	8	8	8	8	2	2	2	2	2
Quad Input Page Program	32h	A23-A16	A15-A8	A7-A0	(D7-D0) ⁽⁹⁾	(D7-D0) ⁽³⁾	...		
Fast Read Quad Output	6Bh	A23-A16	A15-A8	A7-A0	Dummy	Dummy	Dummy	Dummy	(D7-D0) ⁽¹⁰⁾ ...
Number of Clock ⁽¹⁻⁴⁻⁴⁾	8	2 ⁽⁸⁾	2 ⁽⁸⁾	2 ⁽⁸⁾	2	2	2	2	2
Mftr./Device ID Quad I/O	94h	A23-A16	A15-A8	00	Dummy ⁽¹¹⁾	Dummy	Dummy	(MF7-MF0)	(ID7-ID0)
Fast Read Quad I/O	EBh	A23-A16	A15-A8	A7-A0	Dummy ⁽¹¹⁾	Dummy	Dummy	(D7-D0)	

Notes:

- Data bytes are shifted with Most Significant Bit first. Byte fields with data in parenthesis “()” indicate data output from the device on either 1, 2 or 4 IO pins.
- The Status Register contents and Device ID will repeat continuously until /CS terminates the instruction.
- At least one byte of data input is required for Page Program, Quad Page Program and Program Security Registers, up to 256 bytes of data input. If more than 256 bytes of data are sent to the device, the addressing will wrap to the beginning of the page and overwrite previously sent data.
- Write Status Register-1 (01h) can also be used to program Status Register-1&2, see section 8.2.5.
- Security Register Address:
 Security Register 1: A23-16 = 00h; A15-8 = 10h; A7-0 = byte address
 Security Register 2: A23-16 = 00h; A15-8 = 20h; A7-0 = byte address
 Security Register 3: A23-16 = 00h; A15-8 = 30h; A7-0 = byte address
- Dual SPI address input format:
 IO0 = A22, A20, A18, A16, A14, A12, A10, A8 A6, A4, A2, A0, M6, M4, M2, M0
 IO1 = A23, A21, A19, A17, A15, A13, A11, A9 A7, A5, A3, A1, M7, M5, M3, M1
- Dual SPI data output format:
 IO0 = (D6, D4, D2, D0)
 IO1 = (D7, D5, D3, D1)
- Quad SPI address input format:
 IO0 = A20, A16, A12, A8, A4, A0, M4, M0
 IO1 = A21, A17, A13, A9, A5, A1, M5, M1
 IO2 = A22, A18, A14, A10, A6, A2, M6, M2
 IO3 = A23, A19, A15, A11, A7, A3, M7, M3
- Quad SPI data input/output format:
 IO0 = (D4, D0,)
 IO1 = (D5, D1,)
 IO2 = (D6, D2,)
 IO3 = (D7, D3,)
- Fast Read Quad I/O data output format:
 IO0 = (x, x, x, x, D4, D0, D4, D0)
 IO1 = (x, x, x, x, D5, D1, D5, D1)
 IO2 = (x, x, x, x, D6, D2, D6, D2)
 IO3 = (x, x, x, x, D7, D3, D7, D3)
- The first dummy is M7-M0 should be set to Fxh.



8.2 Instruction Descriptions

8.2.1 Write Enable (06h)

The Write Enable instruction (Figure 5) sets the Write Enable Latch (WEL) bit in the Status Register to a 1. The WEL bit must be set prior to every Page Program, Quad Page Program, Sector Erase, Block Erase, Chip Erase, Write Status Register and Erase/Program Security Registers instruction. The Write Enable instruction is entered by driving /CS low, shifting the instruction code “06h” into the Data Input (DI) pin on the rising edge of CLK, and then driving /CS high.

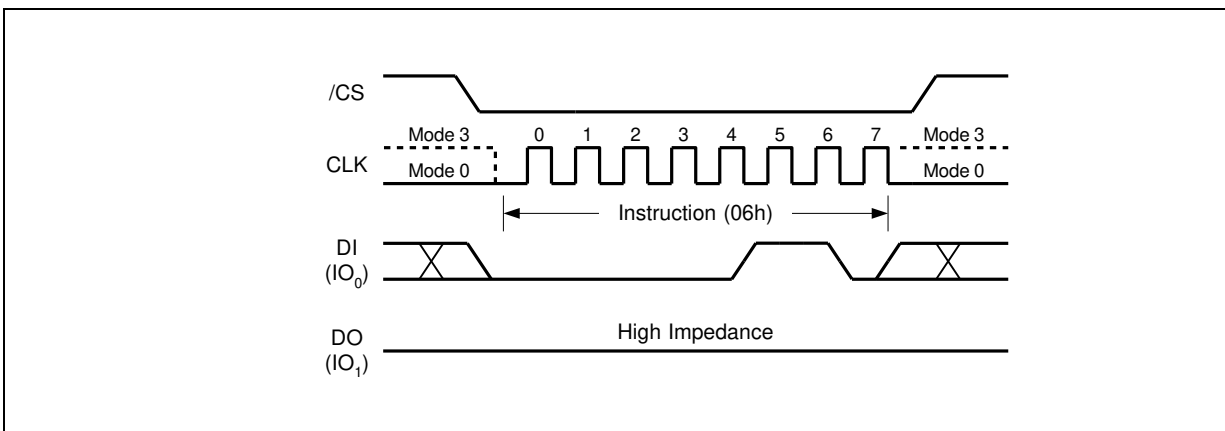


Figure 5. Write Enable Instruction

8.2.2 Write Enable for Volatile Status Register (50h)

The non-volatile Status Register bits described in section 7.1 can also be written to as volatile bits. This gives more flexibility to change the system configuration and memory protection schemes quickly without waiting for the typical non-volatile bit write cycles or affecting the endurance of the Status Register non-volatile bits. To write the volatile values into the Status Register bits, the Write Enable for Volatile Status Register (50h) instruction must be issued prior to a Write Status Register (01h) instruction. Write Enable for Volatile Status Register instruction (Figure 6) will not set the Write Enable Latch (WEL) bit, it is only valid for the Write Status Register instruction to change the volatile Status Register bit values.

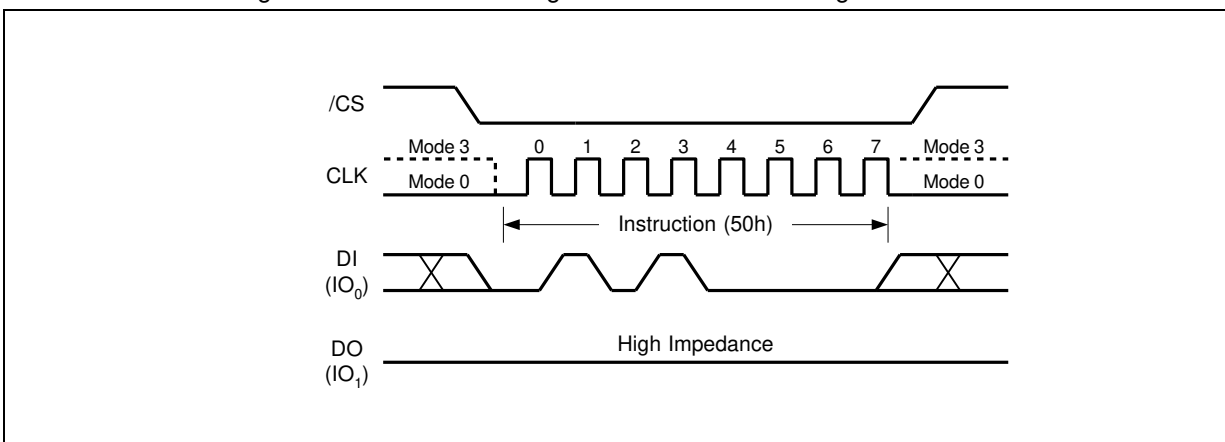


Figure 6. Write Enable for Volatile Status Register Instruction



8.2.3 Write Disable (04h)

The Write Disable instruction (Figure 7) resets the Write Enable Latch (WEL) bit in the Status Register to a 0. The Write Disable instruction is entered by driving /CS low, shifting the instruction code “04h” into the DI pin and then driving /CS high. Note that the WEL bit is automatically reset after Power-up and upon completion of the Write Status Register, Erase/Program Security Registers, Page Program, Quad Page Program, Sector Erase, Block Erase, Chip Erase and Reset instructions.

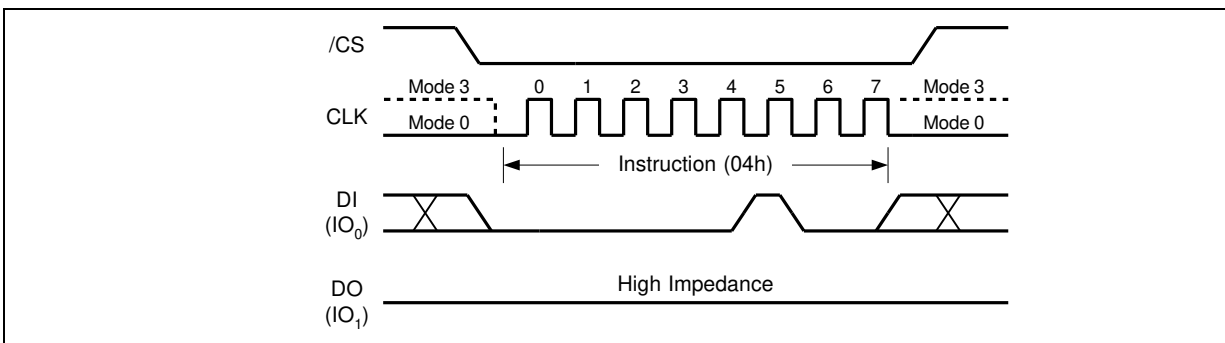


Figure 7. Write Disable Instruction

8.2.4 Read Status Register-1 (05h), Status Register-2 (35h) & Status Register-3 (15h)

The Read Status Register instructions allow the 8-bit Status Registers to be read. The instruction is entered by driving /CS low and shifting the instruction code “05h” for Status Register-1, “35h” for Status Register-2 or “15h” for Status Register-3 into the DI pin on the rising edge of CLK. The status register bits are then shifted out on the DO pin at the falling edge of CLK with most significant bit (MSB) first as shown in Figure 8. Refer to section 7.1 for Status Register descriptions.

The Read Status Register instruction may be used at any time, even while a Program, Erase or Write Status Register cycle is in progress. This allows the BUSY status bit to be checked to determine when the cycle is complete and if the device can accept another instruction. The Status Register can be read continuously, as shown in Figure 8. The instruction is completed by driving /CS high.

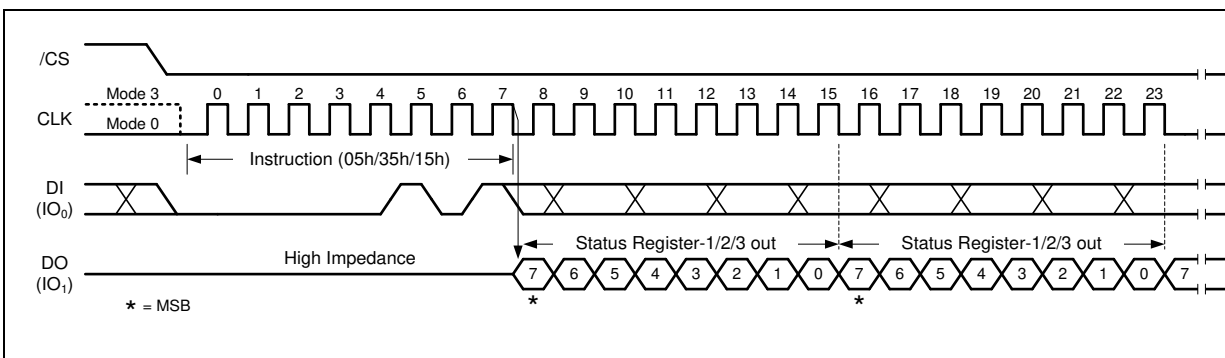


Figure 8. Read Status Register Instruction